
Integrirana vezja - Vrednotenje elektromagnetne združljivosti (EMC) oddajnikov-sprejemnikov - 5. del: Ethernet oddajniki-sprejemniki

Integrated circuits - EMC evaluation of transceivers - Part 5: Ethernet transceivers

Integrierte Schaltungen - Bewertung der elektromagnetischen Verträglichkeit von Sende-Empfangsgeräten - Teil 5: Ethernet-Sende-Empfangsgerät

Circuits intégrés - Evaluation de la CEM des émetteurs-récepteurs - Partie 5: Emetteurs-récepteurs ethernet

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47A/1226/CDV

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TITLE:

Integrated circuits - EMC evaluation of transceivers - Part 5: Ethernet transceivers

PROPOSED STABILITY DATE: 2032

NOTE FROM TC/SC OFFICERS:

All comments on 47A/1211/CD have been reviewed and resolved. SC47A has decided to proceed to the CDV stage.

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